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SPECIFICATION

- · Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- · Samsung P/N :
- CL31B475KAHNFNE

(Reference sheet)

- · Description :
- CAP, 4.7uF, 25V, ±10%, X7R, 1206

A. Samsung Part Number

		<u>CL</u> ①	<u>31</u> ②	<u>В</u> З	<u>475</u> ④	<u>K</u> 5	<mark>4</mark> 6	<u>Н</u> 7	<u>N</u> 8	<u>F</u> 9	<u>N</u> 10	<mark>Е</mark> Ф
1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	1206 (inch	code)		L:	3.20	± 0.20	mm			W:	1.60 ± 0.20 mm
3	Dielectric	X7R				8	Inner	elect	rode			Ni
4	Capacitance	4.7 uF					Term	inatio	n			Cu
5	Capacitance	±10 %					Platir	ng				Sn 100% (Pb Free)
	tolerance					9	Prod	uct				Product for POWER application
6	Rated Voltage	25 V				10	Spec	ial				Reserved for future use
\bigcirc	Thickness	1.60 ± 0.20 mm				1	Pack	aging				Embossed Type, 7" reel

B. Structure & Dimension



Samsung P/N	Dimension(mm)								
Samsung F/N	L	W	Т	BW					
CL31B475KAHNFNE	3.20 ± 0.20	1.60 ± 0.20	1.60 ± 0.20	0.50 ± 0.30					

C. Samsung Reliablility Test and Judgement Condition

CapacitanceWithin specified tolerance $1^{H/L} \pm 10\% / 1.0 \pm 0.2Vrms$ Tan 5 (DF)0.1 max.*A capacitor prior to measuring the capacitance treated at $150^{\circ}C \pm 0/-10^{\circ}C$ for 1 hour and maintai ambient air for 24 ± 2 hours.Insulation10,000Mohm or 100Mohm×//FRated Voltage60~120 sec.ResistanceWhichever is smallerMicroscope (×10)WithstandingNo dielectric breakdown or mechanical breakdown250% of the rated voltageTemperatureX7RKrCharacteristics(From-55°C to 125°C, Capacitance change should be within ±15%)Adhesive Strength of TerminationNo peeling shall be occur on the terminal electrode500g·f, for 10±1 sec.Bending StrengthCapacitance change : within ±12.5%Bending to the limit (1mm) with 1.0mm/sec.SolderabilityMore than 75% of terminal surface is to be soldered newlySolder pot : 270±5°C, 10±1 sec.Vibration TestCapacitance change : capacitance change : within ±5% Tan δ , IR : initial spec.Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)Moisture Resistance IR : IR : <th></th>					
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Resistance Tan δ : 0.125 max 40±2°C, 90~95%RH, 500+12/-0hrs					
IR : 500Mohm or 12.5Mohm × μ F					
Whichever is smaller					
High Temperature Capacitance change : within ±12.5% With ^{150%} of the rated voltage					
Resistance Tan δ : 0.125 max Max. operating temperature					
IR : 1,000Mohm or 25Mohm × ^μ F 1,000+48/-0hrs					
Whichever is smaller					
Temperature Capacitance change : within ±7.5% 1 cycle condition					
CyclingTan δ , IR : initial spec.Min. operating temperature \rightarrow 25°C					
\rightarrow Max. operating temperature \rightarrow 25°C					
5 cycle test					

X The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260±5°C, 30sec.)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

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- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- ④ Military equipment
- *⑤* Disaster prevention/crime prevention equipment
- *ⓐ* Any other applications with the same as or similar complexity or reliability to the applications set forth above.